



Material Content Data Sheet



Sales Product Name	BSC047N08NS3 G			Issued		11. November 2019		
MA#	MA001508098							
Package	PG-TDSON-8-39			Weight*		114.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	3.86	3.86	38612	38612
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.048	0.04		424	
	non noble metal	copper	7440-50-8	48.352	42.31	42.36	422974	423525
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	537	537
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		680	
	plastics	epoxy resin	-	6.144	5.37		53749	
	inorganic material	silicondioxide	60676-86-0	32.666	28.58	34.02	285756	340185
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13297	13297
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1386	1386
solder	non noble metal	tin	7440-31-5	0.070	0.06		609	
	noble metal	silver	7440-22-4	0.087	0.08		761	
	non noble metal	lead	7439-92-1	3.322	2.91	3.05	29056	30426
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.150	0.13		1312	
	non noble metal	copper	7440-50-8	16.910	14.79	14.93	147925	149429
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2599	2603
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com